

Inductorless -2x Boost/Buck Regulator

Features

- Input Range 2.5V to 5.5V
- Regulated Output Options from -3.0 to -5.0V
- Output Current 20mA (max)
- 200kHz Internal Oscillator Frequency
- External Synchronizing Clock Input
- Logic Level Shutdown
 - 1 μ A (max) Supply Current
- Available in 8-Pin MSOP Package

Applications

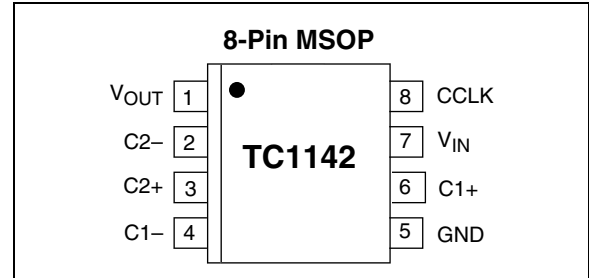
- Cellular Phones
- Battery Powered/Portable Equipment

Device Selection Table

Part Number	Output Voltage (V)*	Package	Operating Temp. Range
TC1142-3.0EUA	3.0	8-Pin MSOP	-40°C to +85°C
TC1142-4.0EUA	4.0	8-Pin MSOP	-40°C to +85°C
TC1142-5.0EUA	5.0	8-Pin MSOP	-40°C to +85°C

*Other output voltages are available (-3.5V and -4.5V). Please contact Microchip Technology Inc. for details.

Package Type



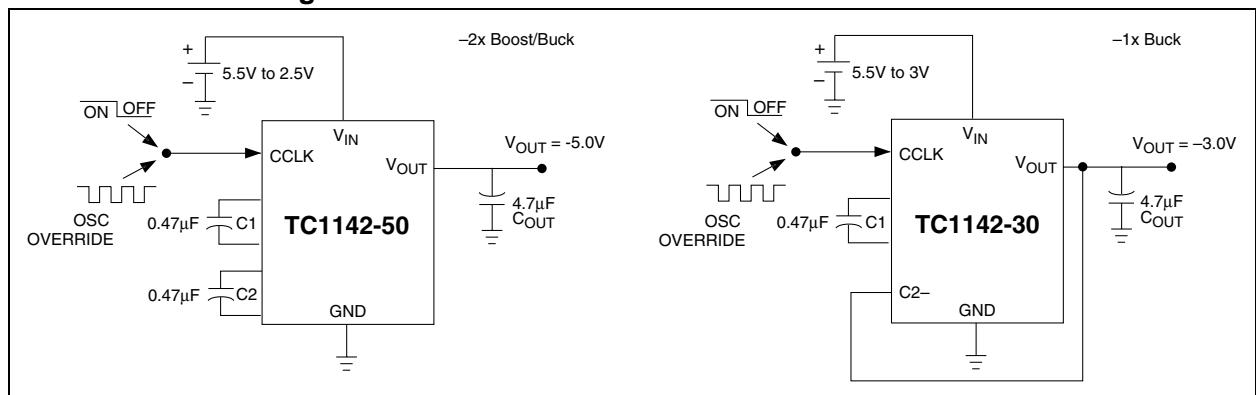
General Description

The TC1142 generates a regulated negative voltage from -3V to -5V at 20mA from an input of 2.5V to 5.5V, using only three external capacitors. Other boost/buck switching regulators must use an inductor, which is larger and radiates EMI. An internal voltage comparator inhibits the charge pump when V_{OUT} is more negative than the regulated value (per the ordering option). The values of flying capacitors C1 and C2 are chosen to be less than C_{OUT} in order to reduce the ripple generated from regulating V_{OUT} in this manner. The TC1142 also can be used as a -1x buck regulator by omitting C2, and connecting the C2 pin to V_{OUT} .

The part goes into shutdown when the CCLK input is driven low. When in shutdown mode, the part draws a maximum of 1 μ A. When CCLK is pulled high, the part runs from the internal 200kHz oscillator. The device may be run with an external clock, provided the frequency is greater than 3kHz and less than 500kHz.

The TC1142 comes in a space-saving MSOP package.

Functional Block Diagram



TC1142

1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings*

Supply Voltage (V_{IN}) with C_{OUT} Connected 6.5V
 CCLK Voltage -0.3V to ($V^+ + 0.3V$)
 Power Dissipation 320mW
 Operating Temperature Range
 8-Pin MSOP -40°C to +85°C
 Storage Temperature Range -65°C to +160°C

*Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions above those indicated in the operation sections of the specifications is not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

TC1142 ELECTRICAL SPECIFICATIONS

Electrical Characteristics: $R_L = \infty$, $V_{IN} = 3.2V$, Mode = -2x, $C_1 = C_2 = 0.47\mu F$ (Note 1), $CCLK = V_{IH}$, $C_{OUT} = 4.7\mu F$, for $V_R = 3V$, $V_{IN} = 3.5V$, $T_A = T_{MIN}$ to T_{MAX} , unless otherwise noted.

Symbol	Parameter	Min	Typ	Max	Units	Test Conditions
V_{IN}	Supply Voltage	2.5	—	5.5	V	
V_{OUT}	Output Voltage	$-(V_R + 0.2)$	$-V_R$	$-(V_R - 0.2)$	V	$I_L = 0mA$ (Note 2)
V_{P-P}	Output Ripple	—	100	—	mV	$I_L = 10mA$
I_{SUPPLY}	Supply Current	—	200	400	μA	
$I_{SUPPLY1}$		—	0.1	1	μA	CCLK = 0V
R_{OUTCL}	Closed-Loop Output Resistance	—	2	6	Ω	
R_{OUT}	Open-Loop Output Resistance	—	30	—	Ω	(Note 3)
f_{OSC}	Internal Oscillator Frequency	150	200	275	kHz	
f_{CCLK}	External Clock Frequency, Typical	3	—	500	kHz	(Note 4)
P_{EFF}	Power Efficiency	70	76	—	%	$I_L = 10mA$, $V_R = 5V$; (See Equation 3-5)
V_{IH}	CCLK Input High Threshold	2.2	—	—	V	
V_{IL}	CCLK Input Low Threshold	—	—	1.0	V	

- Note**
- 1: Assume C_1 and C_2 have an ESR of 1Ω .
 - 2: V_R is the voltage output specified in the ordering option.
 - 3: Measured in -1x Mode. For $V_R = 3V$, $V_{IN} = 2.5V$.
 - 4: CCLK is driven with an external clock. Minimum frequency = $1/2t_0$ at 50% duty cycle, where t_0 is the counter timeout period.

2.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 2-1.

TABLE 2-1: PIN FUNCTION TABLE

Pin No. (8-Pin MSOP)	Symbol	Description
1	V_{OUT}	Regulated negative output voltage.
2	C2-	Negative terminal of flying capacitor C2.
3	C2+	Positive terminal of flying capacitor C2.
4	C1-	Negative terminal of flying capacitor C1.
5	GND	Power supply ground.
6	C1+	Positive terminal of flying capacitor C1.
7	V_{IN}	Power supply positive voltage input (2.5V to 5.5V).
8	CCLK	Clock control input: If low, the TC1142 is in Shutdown mode (1 μ A, max). If high, the TC1142 runs off the internal oscillator (200kHz, typ.). CCLK can be overridden by an external oscillator from 3kHz to 500kHz.

3.0 DETAILED DESCRIPTION

The TC1142 inductorless -2x boost/buck regulator is an inverting charge pump that uses a pulse-frequency modulation (PFM) control scheme to produce a regulated negative output voltage, $-V_R$, between -3V and -5V (depending on the output voltage option) at 20mA maximum load. Output voltage regulation is achieved by gating ON the clock to the charge pump for a single half-clock period whenever the output is more positive than V_R , and gating it OFF when the output is more negative than $-V_R$. The resulting PFM of the clock applied to the charge pump has a high frequency spectral content consisting only of clock harmonics. When using an external clock, the transient noise is then synchronized to the clock and is easier to filter in sensitive applications.

The TC1142 also can be used as a -1x boost/buck regulator by omitting the C2 capacitor and connecting the C2- pin to V_{OUT} .

The PFM control scheme minimizes supply current at small loads and permits the use of low value flying capacitors, which saves on printed circuit board space and cost. Due to the TC1142's doubling and inverting charge pump mechanism, the output voltage is limited to $-2V_{IN}$. To produce a -5V regulated output, for example, a minimum input voltage of 2.5V is required at V_{IN} .

The CCLK pin of the TC1142 has three functions: It can select the internal 200kHz oscillator (when held HIGH), put the TC1142 into shutdown (when held LOW), or provide an external clock input. To achieve this functionality, an internal counter is reset by any positive transition at the CCLK pin, but will time out in typically 160 μ sec (i.e., a frequency higher than about 3kHz). If the counter times out following the last positive transition, then the internal clock will be gated through to the charge pump if CCLK is HIGH, or the device will enter shutdown mode if it is LOW. To enter shutdown, CCLK must be LOW and the counter must have timed out. These timing diagrams are shown in Figure 3-4.

A functional circuit diagram of the TC1142 is shown in Figure 3-1. The output voltage V_{OUT} is compared to an on-chip reference voltage, and the comparator output is used to gate the charge pump clock. The charge pump is a negative voltage doubler and has two phases of operation which are further illustrated in Figure 3-2 and Figure 3-3. In phase 1, shown in Figure 3-2, the flying capacitor C1 charges the flying capacitor C2 while the device load is totally serviced by the charge stored on the reservoir capacitor C_{OUT} . In phase 2, shown in Figure 3-3, the capacitor C1 is recharged to V_{IN} while the capacitor C2 transfers its charge to the reservoir capacitor C_{OUT} .

In normal operation, the TC1142 charge pump stays in phase 2 and only switches to phase 1 as required to maintain output voltage regulation.

FIGURE 3-1: FUNCTIONAL CIRCUIT DIAGRAM

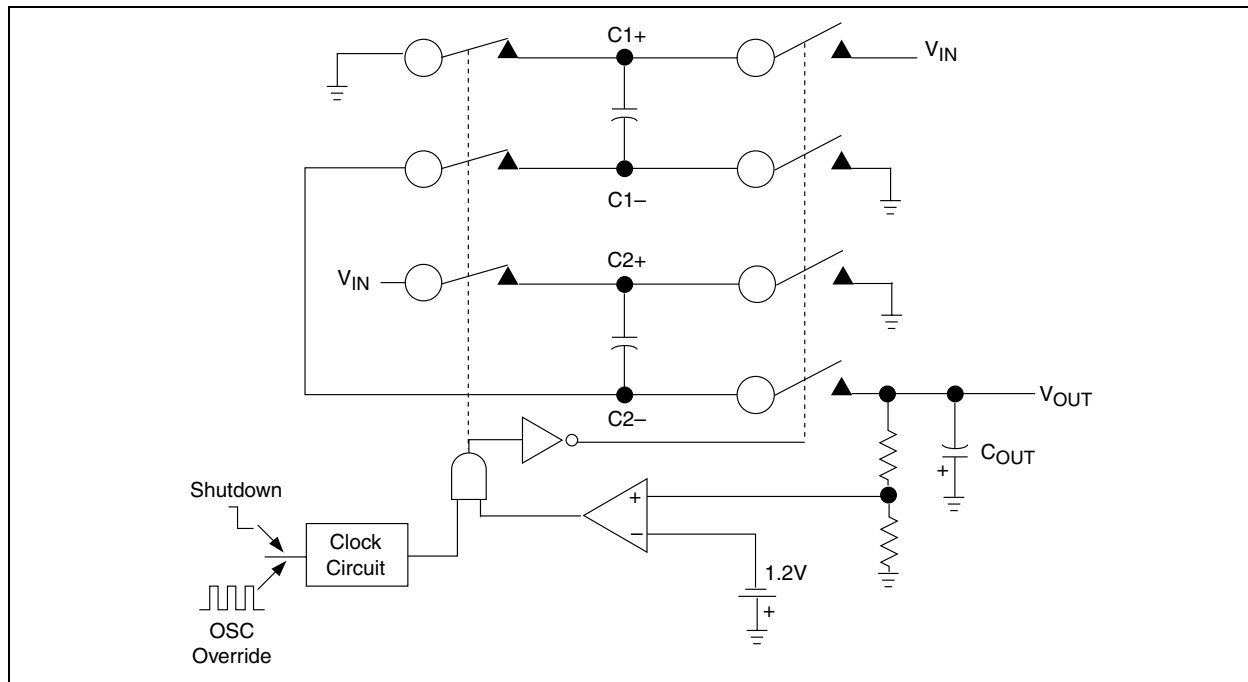


FIGURE 3-2: TC1142 PHASE 1

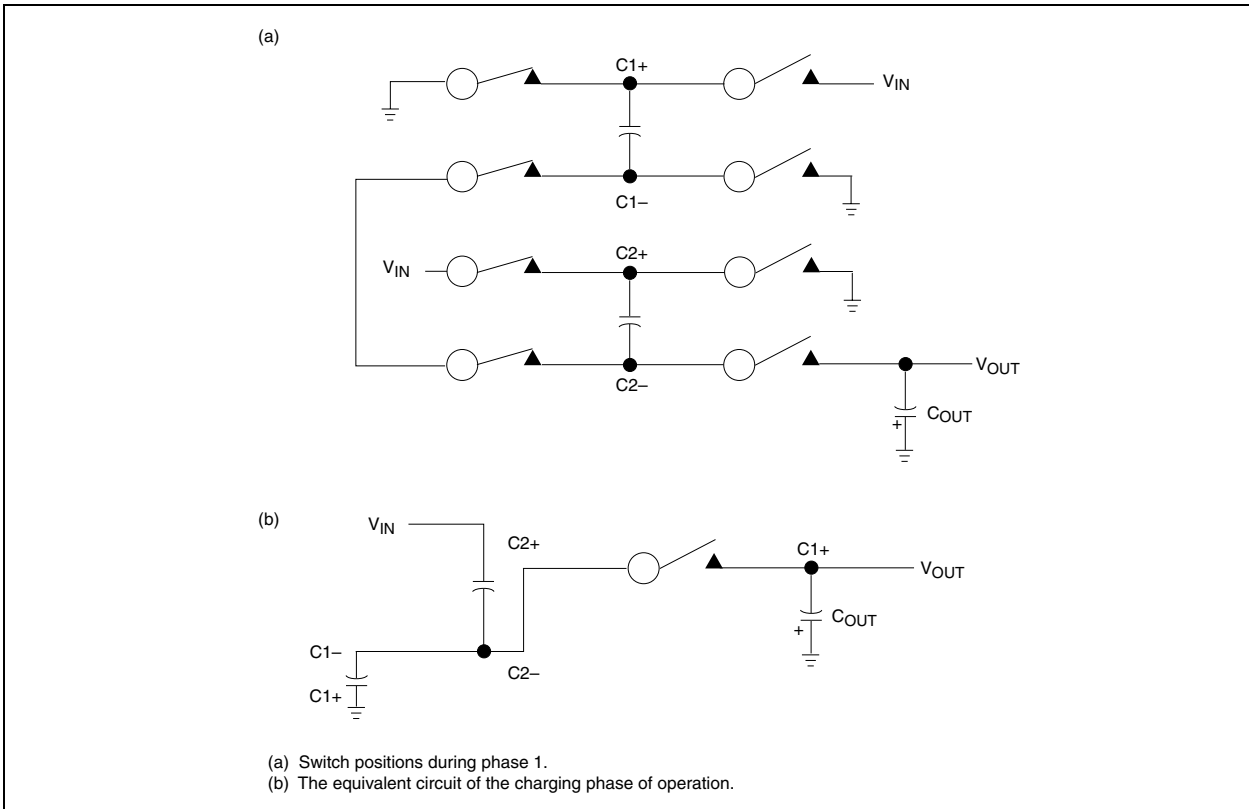
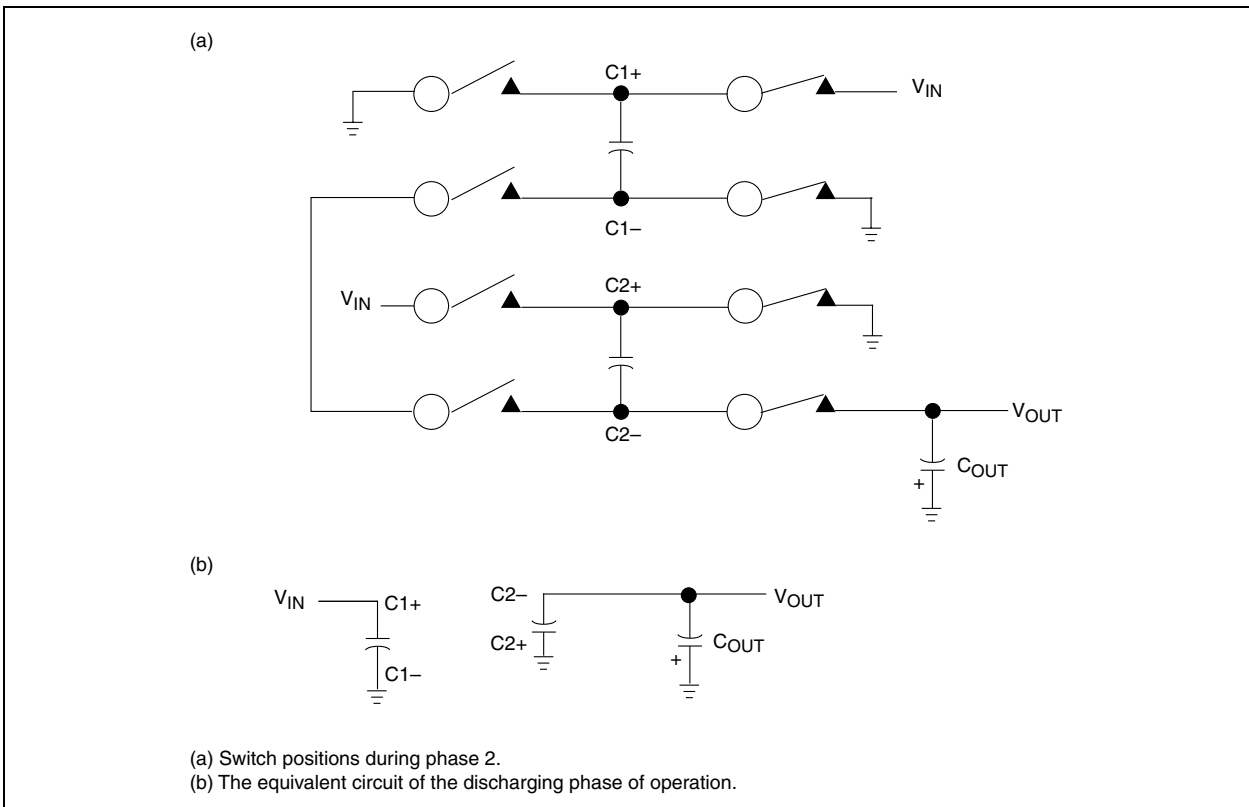


FIGURE 3-3: TC1142 PHASE 2



3.1 Output Voltage and Ripple

For a -2x boost:

a.) For unregulated operation when $V_{IN} \leq \left| \frac{V_R}{2} \right|$.

In this case, the output voltage is given by:

EQUATION 3-1:

$$V_{OUT} = -|2V_{IN}| + I_O R_{OUT}$$

$$\text{where } R_{OUT} = \frac{1}{f} \left(\frac{1}{C_1} + \frac{1}{C_2} \right) + \frac{R_S C_2}{(C_2 + C_{OUT})}$$

Here, f is the clock frequency and R_S is the total ON resistance of the switches connecting C_2 to GND and V_{OUT} in phase 2 of the charge pump operating cycle with the equivalent series resistance (ESR) of C_2 .

The output ripple voltage is given by:

EQUATION 3-2:

$$V_{RIPPLE} = I_O R_{RIPPLE}$$

$$\text{where } R_{RIPPLE} = \frac{1}{2f(C_2 + C_{OUT})} + \frac{1}{2fC_{OUT}} + \frac{ESR C_2}{(C_2 + C_{OUT})}$$

Here, ESR is the equivalent series resistance of C_{OUT} .

b.) For regulated operation when $V_{IN} > \left| \frac{V_R}{2} \right|$.

In this case, the TC1142 is held in phase 2 until the output voltage drops below V_R . When this occurs, the TC1142 reverts to phase 1 for a half period of the clock, during which C_2 is charged from C_1 . At the end of this half-period, C_2 is reconnected to C_{OUT} to boost the output voltage. During the phase 1 time period, the output voltage will drop below V_R before it is boosted back, so the minimum output voltage is approximated by:

EQUATION 3-3:

$$V_{OUTMIN} = -|V_R| + I_O R_{OUT}$$

$$\text{where } R_{OUT} = \frac{1}{2fC_{OUT}} + \frac{ESR C_2}{(C_2 + C_{OUT})}$$

The output ripple voltage is given approximately by:

EQUATION 3-4:

$$V_{RIPPLE} = \frac{(2V_{IN} - |V_R| + ESR I_O C_2 \left(\frac{1}{C_1} + \frac{1}{C_2} \right))}{N}$$

$$\text{where } N = \left(\frac{1}{C_1} + \frac{1}{C_2} \right) (C_2 + C_{OUT})$$

For values of V_{IN} higher than $|V_R/2|$ by several hundred mV, the effect on ripple of the ESR of C_{OUT} can be neglected compared to the "overdrive" effect of V_{IN} .

Here, it can be seen that V_{RIPPLE} increases with increasing V_{IN} , but can be minimized by choosing small C_1 and C_2 values and a large C_{OUT} value.

3.2 Capacitor Selection

To maintain low output impedance and ripple, it is recommended that capacitors with low equivalent series resistance (ESR) be used. Additionally, larger values of the output capacitor and smaller values of the flying capacitors will reduce output ripple. For a capacitor value of $4.7\mu\text{F}$ for C_{OUT} , and values of $0.47\mu\text{F}$ for C_1 and C_2 , the typical output impedance of the TC1142 in regulation is 0.5Ω . For the capacitor ESR not to have a noticeable effect on output impedance, it should not be larger than $1/2fC_{OUT}$. This also makes its effect on ripple voltage negligible. For $V_{IN} = 3.2\text{V}$ and $V_R = -5\text{V}$, the output ripple voltage is less than 70mV_{PP} . Table 3-1 summarizes output ripple versus capacitor size for an input voltage of 3.2V and a regulated output voltage of -5V .

Surface mount ceramic capacitors are preferred for their small size, low cost and low ESR. Low ESR tantalum capacitors also are acceptable. See Table 3-2 for a list of suggested capacitor suppliers.

TABLE 3-1: VOLTAGE RIPPLE VS. C1/C2 FLYING CAPACITORS AND OUTPUT CAPACITOR C_{OUT} ESR = 0.1Ω , $I_{OUT} = 20\text{mA}$

C1, C2 (μF)	C_{OUT} (μF)	V_{IN} (V)	V_{OUT} (V)	V_{RIPPLE} (mV)
0.1	4.7	3.2	-5	14.6
0.22	4.7	3.2	-5	31.4
0.33	4.7	3.2	-5	46.1
0.47	4.7	3.2	-5	63.9
0.68	4.7	3.2	-5	88.7
1.0	4.7	3.2	-5	123.2
0.1	10	3.2	-5	7.0
0.22	10	3.2	-5	15.1
0.33	10	3.2	-5	22.4
0.47	10	3.2	-5	31.5
0.68	10	3.2	-5	44.7
1.0	10	3.2	-5	63.8

TABLE 3-2: LOW ESR SURFACE-MOUNT CAPACITOR MANUFACTURERS

Manufacturer	Type	Phone
AVX Corp.	TPS series surface-mount tantalum X7R type surface-mount ceramic	803-448-9411
Matsuo	267 series surface-mount tantalum X7R type surface-mount ceramic	714-969-2491
Sprague	593D, 594D, 595D series surface-mount tantalum	207-324-4140
Murata	Ceramic chip capacitors	800-831-9172
Taiyo Yuden	Ceramic chip capacitors	800-348-2496
Token	Ceramic chip capacitors	408-432-8020

3.3 Power Efficiency

Assuming the output is loaded with at least 20% of the maximum available output current, the power efficiency of the TC1142 can be estimated using the following equation:

EQUATION 3-5:

$$\eta = \frac{|V_R|}{2(V_{IN})}$$

For example, a 3.2 Volt V_{IN} , and a -5 Volt V_R will have an efficiency of approximately 78%. For loads less than 20% of the maximum available output current, the power efficiency will be substantially reduced. Other factors that affect the actual efficiency include:

1. Losses from power consumed by the internal oscillator (if used).
2. I^2R losses due to the on-resistance of the MOSFET charge pump switches.
3. Charge pump capacitor losses due to ESR.
4. Losses that occur during charge transfer (from the flying capacitors to the output capacitor) when a voltage difference exists between these capacitors.

3.4 Choice of -2x or -1x Connections

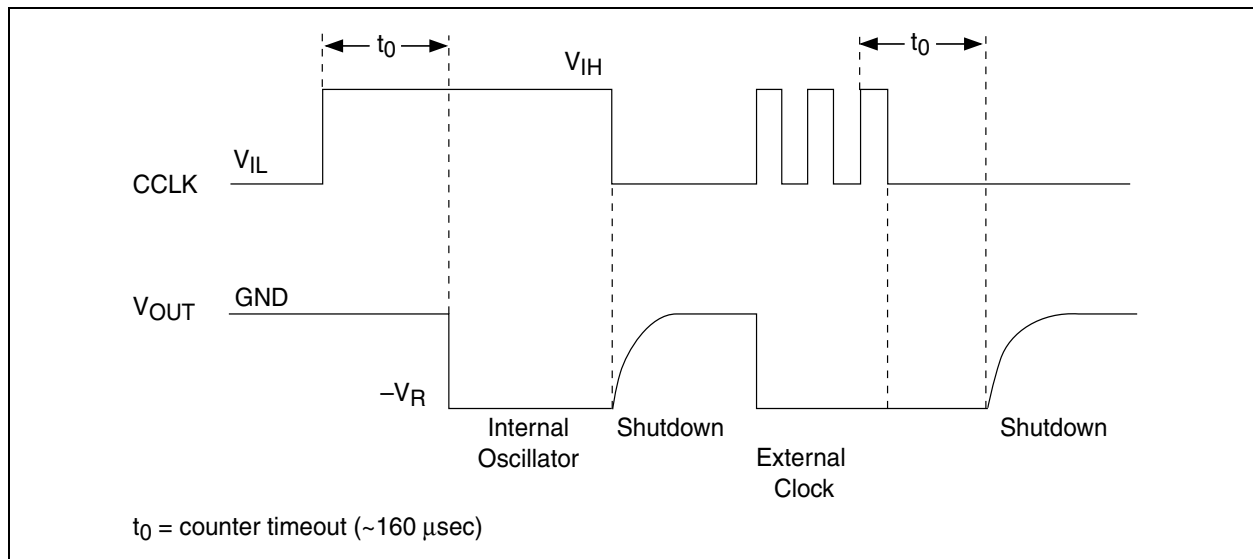
If required output voltage can be achieved using a -1x configuration then this is preferred for the following reasons:

1. Power efficiency is improved from $V_R/2V_{IN}$ to V_R/V_{IN}
2. Only one flying capacitor needed
3. The output ripple becomes proportional to $V_{IN} - V_R$ rather than $2V_{IN} - V_R$.

3.5 Layout Considerations

Proper layout is important to obtain optimal performance. Mount capacitors as close to their connecting device pins as possible to minimize stray inductance and capacitance. It is recommended that a large ground plane be used to reduce noise leakage into other circuitry.

FIGURE 3-4: TIMING DIAGRAM



TC1142

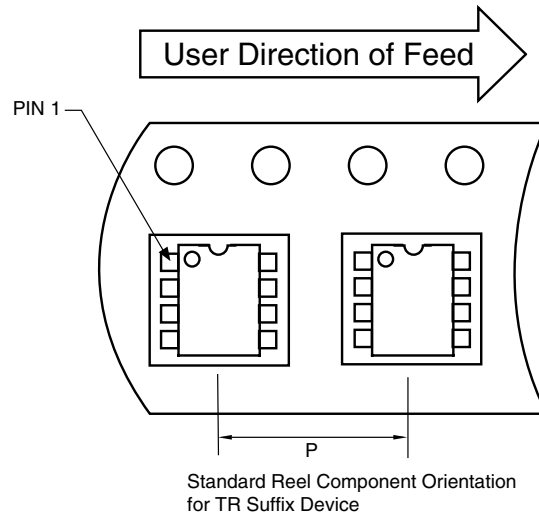
4.0 PACKAGING INFORMATION

4.1 Package Marking Information

Package marking data not available at this time.

4.2 Taping Form

Component Taping Orientation for 8-Pin MSOP Devices

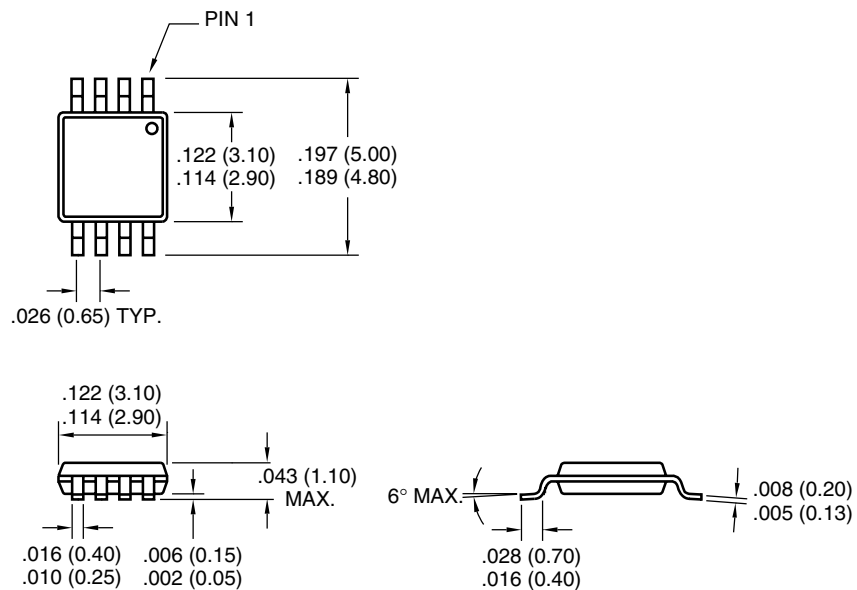


Carrier Tape, Number of Components Per Reel and Reel Size

Package	Carrier Width (W)	Pitch (P)	Part Per Full Reel	Reel Size
8-Pin MSOP	12 mm	8 mm	2500	13 in

4.3 Package Dimensions

8-Pin MSOP



Dimensions: inches (mm)

Sales and Support

Data Sheets

Products supported by a preliminary Data Sheet may have an errata sheet describing minor operational differences and recommended workarounds. To determine if an errata sheet exists for a particular device, please contact one of the following:

1. Your local Microchip sales office
2. The Microchip Corporate Literature Center U.S. FAX: (480) 792-7277
3. The Microchip Worldwide Site (www.microchip.com)

Please specify which device, revision of silicon and Data Sheet (include Literature #) you are using.

New Customer Notification System

Register on our web site (www.microchip.com/cn) to receive the most current information on our products.

TC1142

NOTES:

Information contained in this publication regarding device applications and the like is intended through suggestion only and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications. No representation or warranty is given and no liability is assumed by Microchip Technology Incorporated with respect to the accuracy or use of such information, or infringement of patents or other intellectual property rights arising from such use or otherwise. Use of Microchip's products as critical components in life support systems is not authorized except with express written approval by Microchip. No licenses are conveyed, implicitly or otherwise, under any intellectual property rights.

Trademarks


The Microchip name and logo, the Microchip logo, FilterLab, KEELOQ, microID, MPLAB, PIC, PICmicro, PICMASTER, PICSTART, PRO MATE, SEEVAL and The Embedded Control Solutions Company are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

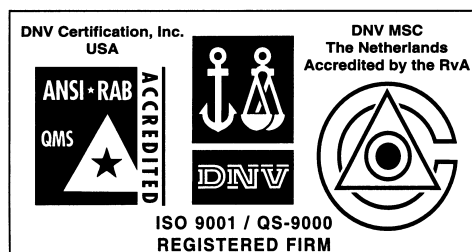
dsPIC, ECONOMONITOR, FanSense, FlexROM, fuzzyLAB, In-Circuit Serial Programming, ICSP, ICEPIC, microPort, Migratable Memory, MPASM, MPLIB, MPLINK, MPSIM, MXDEV, PICC, PICDEM, PICDEM.net, rfPIC, Select Mode and Total Endurance are trademarks of Microchip Technology Incorporated in the U.S.A.

Serialized Quick Turn Programming (SQTP) is a service mark of Microchip Technology Incorporated in the U.S.A.

All other trademarks mentioned herein are property of their respective companies.

© 2002, Microchip Technology Incorporated, Printed in the U.S.A., All Rights Reserved.

 Printed on recycled paper.



Microchip received QS-9000 quality system certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona in July 1999 and Mountain View, California in March 2002. The Company's quality system processes and procedures are QS-9000 compliant for its PICmicro® 8-bit MCUs, KEELOQ® code hopping devices, Serial EEPROMs, microperipherals, non-volatile memory and analog products. In addition, Microchip's quality system for the design and manufacture of development systems is ISO 9001 certified.



MICROCHIP

WORLDWIDE SALES AND SERVICE

AMERICAS

Corporate Office

2355 West Chandler Blvd.
Chandler, AZ 85224-6199
Tel: 480-792-7200 Fax: 480-792-7277
Technical Support: 480-792-7627
Web Address: <http://www.microchip.com>

Rocky Mountain

2355 West Chandler Blvd.
Chandler, AZ 85224-6199
Tel: 480-792-7966 Fax: 480-792-7456

Atlanta

500 Sugar Mill Road, Suite 200B
Atlanta, GA 30350
Tel: 770-640-0034 Fax: 770-640-0307

Boston

2 Lan Drive, Suite 120
Westford, MA 01886
Tel: 978-692-3848 Fax: 978-692-3821

Chicago

333 Pierce Road, Suite 180
Itasca, IL 60143
Tel: 630-285-0071 Fax: 630-285-0075

Dallas

4570 Westgrove Drive, Suite 160
Addison, TX 75001
Tel: 972-818-7423 Fax: 972-818-2924

Detroit

Tri-Atria Office Building
32255 Northwestern Highway, Suite 190
Farmington Hills, MI 48334
Tel: 248-538-2250 Fax: 248-538-2260

Kokomo

2767 S. Albright Road
Kokomo, Indiana 46902
Tel: 765-864-8360 Fax: 765-864-8387

Los Angeles

18201 Von Karman, Suite 1090
Irvine, CA 92612
Tel: 949-263-1888 Fax: 949-263-1338

New York

150 Motor Parkway, Suite 202
Hauppauge, NY 11788
Tel: 631-273-5305 Fax: 631-273-5335

San Jose

Microchip Technology Inc.
2107 North First Street, Suite 590
San Jose, CA 95131
Tel: 408-436-7950 Fax: 408-436-7955

Toronto

6285 Northam Drive, Suite 108
Mississauga, Ontario L4V 1X5, Canada
Tel: 905-673-0699 Fax: 905-673-6509

ASIA/PACIFIC

Australia

Microchip Technology Australia Pty Ltd
Suite 22, 41 Rawson Street
Epping 2121, NSW
Australia
Tel: 61-2-9868-6733 Fax: 61-2-9868-6755

China - Beijing

Microchip Technology Consulting (Shanghai)
Co., Ltd., Beijing Liaison Office
Unit 915
Bei Hai Wan Tai Bldg.
No. 6 Chaoyangmen Beidajie
Beijing, 100027, No. China
Tel: 86-10-85282100 Fax: 86-10-85282104

China - Chengdu

Microchip Technology Consulting (Shanghai)
Co., Ltd., Chengdu Liaison Office
Rm. 2401, 24th Floor,
Ming Xing Financial Tower
No. 88 TIDU Street
Chengdu 610016, China
Tel: 86-28-6766200 Fax: 86-28-6766599

China - Fuzhou

Microchip Technology Consulting (Shanghai)
Co., Ltd., Fuzhou Liaison Office
Unit 28F, World Trade Plaza
No. 71 Wusi Road
Fuzhou 350001, China
Tel: 86-591-7503506 Fax: 86-591-7503521

China - Shanghai

Microchip Technology Consulting (Shanghai)
Co., Ltd.
Room 701, Bldg. B
Far East International Plaza
No. 317 Xian Xia Road
Shanghai, 200051
Tel: 86-21-6275-5700 Fax: 86-21-6275-5060

China - Shenzhen

Microchip Technology Consulting (Shanghai)
Co., Ltd., Shenzhen Liaison Office
Rm. 1315, 13/F, Shenzhen Kerry Centre,
Renminnan Lu
Shenzhen 518001, China
Tel: 86-755-2350361 Fax: 86-755-2366086

Hong Kong

Microchip Technology Hongkong Ltd.
Unit 901-6, Tower 2, Metroplaza
223 Hing Fong Road
Kwai Fong, N.T., Hong Kong
Tel: 852-2401-1200 Fax: 852-2401-3431

India

Microchip Technology Inc.
India Liaison Office
Divyasree Chambers
1 Floor, Wing A (A3/A4)
No. 11, O'Shaugnessey Road
Bangalore, 560 025, India
Tel: 91-80-2290061 Fax: 91-80-2290062

Japan

Microchip Technology Japan K.K.
Benex S-1 6F
3-18-20, Shinyokohama
Kohoku-Ku, Yokohama-shi
Kanagawa, 222-0033, Japan
Tel: 81-45-471- 6166 Fax: 81-45-471-6122

Korea

Microchip Technology Korea
168-1, Youngbo Bldg. 3 Floor
Samsung-Dong, Kangnam-Ku
Seoul, Korea 135-882
Tel: 82-2-554-7200 Fax: 82-2-558-5934

Singapore

Microchip Technology Singapore Pte Ltd.
200 Middle Road
#07-02 Prime Centre
Singapore, 188980
Tel: 65-6334-8870 Fax: 65-6334-8850

Taiwan

Microchip Technology Taiwan
11F-3, No. 207
Tung Hua North Road
Taipei, 105, Taiwan
Tel: 886-2-2717-7175 Fax: 886-2-2545-0139

EUROPE

Denmark

Microchip Technology Nordic ApS
Regus Business Centre
Lautrup høj 1-3
Ballerup DK-2750 Denmark
Tel: 45 4420 9895 Fax: 45 4420 9910

France

Microchip Technology SARL
Parc d'Activite du Moulin de Massy
43 Rue du Saule Trapu
Batiment A - 1er Etage
91300 Massy, France
Tel: 33-1-69-53-63-20 Fax: 33-1-69-30-90-79

Germany

Microchip Technology GmbH
Gustav-Heinemann Ring 125
D-81739 Munich, Germany
Tel: 49-89-627-144 0 Fax: 49-89-627-144-44

Italy

Microchip Technology SRL
Centro Direzionale Colleoni
Palazzo Taurus 1 V. Le Colleoni 1
20041 Agrate Brianza
Milan, Italy
Tel: 39-039-65791-1 Fax: 39-039-6899883

United Kingdom

Arizona Microchip Technology Ltd.
505 Eskdale Road
Winnersh Triangle
Wokingham
Berkshire, England RG41 5TU
Tel: 44 118 921 5869 Fax: 44-118 921-5820

03/01/02

